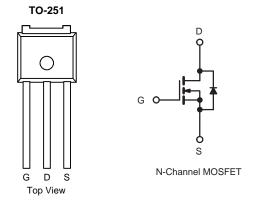


N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A)	Q _g (Typ.)			
30	0.07 at V _{GS} = 10 V	53	19 nC			
	0.09 at V _{GS} = 4.5 V	48	19110			



FEATURES

- Halogen-free
- TrenchFET® Gen III Power MOSFET
- 100 % R_g Tested 100 % UIS Tested

APPLICATIONS

- DC/DC Conversion
 - System Power

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	
-	T _C = 25 °C		53	
Continuous Prain Current (T. – 150 °C)	T _C = 70 °C	1-	41	
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	- I _D	14 ^{b, c}	Α.
	T _A = 70 °C		10 ^{b, c}	
Pulsed Drain Current		I _{DM}	165	
Avalanche Current	che Current L = 0.1 mH		25	
Avalanche Energy	L = U.1 IIII	E _{AS}	40	mJ
Continuous Source-Drain Diode Current	T _C = 25 °C	1	15	A
Continuous Source-Drain Diode Current	T _A = 25 °C	- I _S	2.9 ^{b, c}	^
	T _C = 25 °C		28	
Maximum Power Dissipation	T _C = 70 °C	P _D	18	w
Maximum Fower Dissipation	T _A = 25 °C	L D	3.5 ^{b, c}	VV
	T _A = 70 °C		2.2 ^{b, c}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C
Soldering Recommendations (Peak Tempera		260		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient	t ≤ 10 s	R _{thJA}	29	36	°C/W		
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	3.6	4.5]		

- a. Based on T_C = 25 °C.
 b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.



2

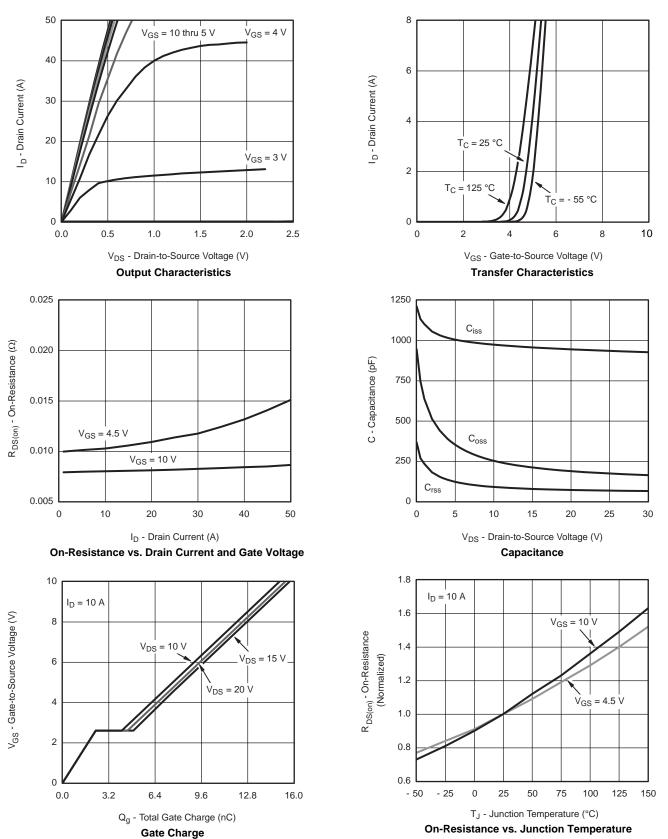
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static				•		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		33		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	i _D = 230 μA		- 5		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	1.2		3.0	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V			1	
Zero Gate Voltage Drain Current		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			5	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	15			Α
During Courses Co. Otata Danieta and		$V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$		0.070		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_{D} = 7 \text{ A}$		0.090		
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 10 A		24		S
Dynamic ^b			I.	•		
Input Capacitance	C _{iss}			1400		
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		200		pF
Reverse Transfer Capacitance	C _{rss}			150		
T. 10 . 0		$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$		33		nC
Total Gate Charge				18		
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		7.3		
Gate-Drain Charge	Q_{gd}			6.2		
Gate Resistance	R_{g}	f = 1 MHz	0.2	0.8	1.6	Ω
Turn-On Delay Time	t _{d(on)}			15	30	
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		12	24	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 10 A, V_{GEN} = 4.5 V, R_g = 1 Ω		13	26	
Fall Time	t _f			10	20	
Turn-On Delay Time	t _{d(on)}			9	18	ns
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		9	18	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 10$ A, $V_{GEN}=10$ V, $R_g=1$ Ω		14	28	
Fall Time	t _f			8	16	
Drain-Source Body Diode Characteristi	cs			•		
Continuous Source-Drain Diode Current	I _S	$T_C = 25 ^{\circ}C$			16	۸
Pulse Diode Forward Current	I _{SM}				32	Α
Body Diode Voltage	V_{SD}	I _S = 3 A, V _{GS} = 0 V		0.78	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			17	34	ns
Body Diode Reverse Recovery Charge	Q _{rr}	L = 10 A dl/dt = 100 A/up T = 25 °C		9.5	19	nC
Reverse Recovery Fall Time	t _a	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		10		
Reverse Recovery Rise Time	t _b			7		ns

Notes:

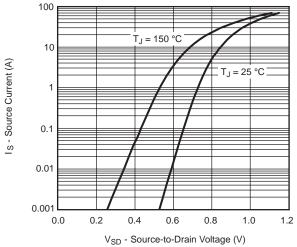
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

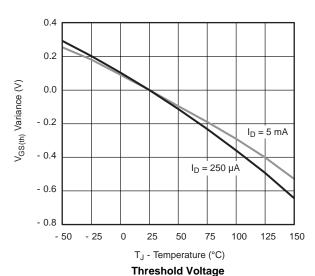








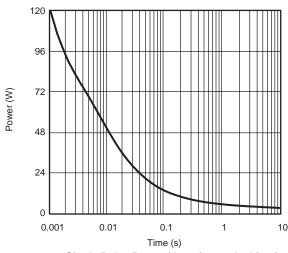
Source-Drain Diode Forward Voltage



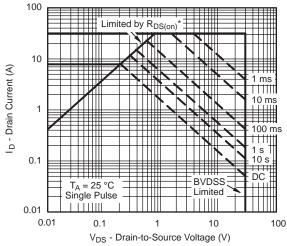
0.06 $I_D = 10^{\circ} A$ 0.05 $R_{DS(on)}$ - On-Resistance (Ω) 0.04 0.03 T_J = 125 °C 0.02 0.01 $T_J = 25 \, ^{\circ}C$ 0.00 2 3 0 4 5

V_{GS} - Gate-to-Source Voltage (V)

On-Resistance vs. Gate-to-Source Voltage



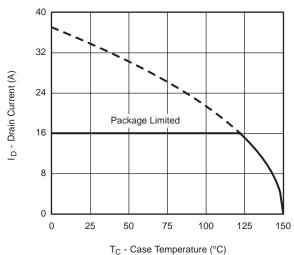
Single Pulse Power (Junction-to-Ambient)



* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

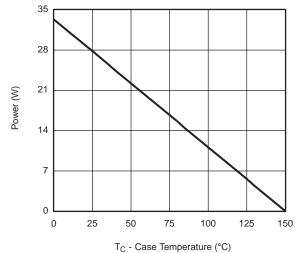
Safe Operating Area, Junction-to-Ambient

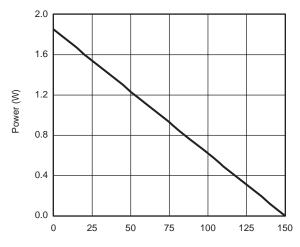




Current Dereting*







T_A - Case Temperature (°C)

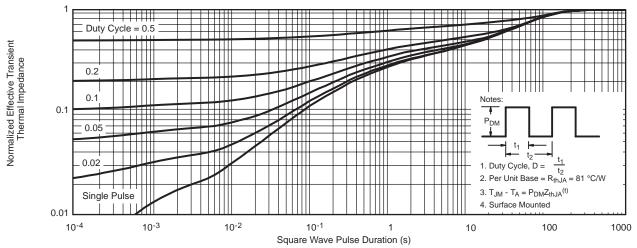
E-mail: China@VBsemi TEL:86-755-83251052

Power, Junction-to-Case

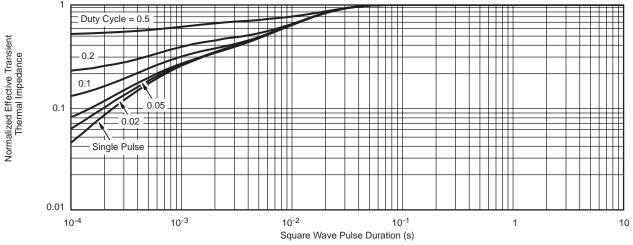
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





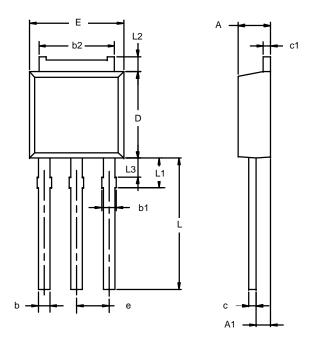
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case



TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

	MILLIN	IETERS	INC	HES	
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090 BSC		
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346					

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